

AMENDMENTS TO THE CLAIMS

Claims 1-10, 20-22 and 29-39 (cancelled).

11. (Original) A curable composition comprising:

(a) an epoxy resin;

(b) a latent fluxing agent which liberates a phenolic compound or a carboxylic acid containing compound when heated above 140°C; and

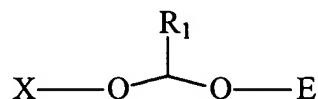
(c) a compound for effecting cure of the epoxy resin.

12. (Original) The composition of claim 11, wherein the latent fluxing agent is an α -alkoxyalkyl ester of a carboxyl-containing compound.

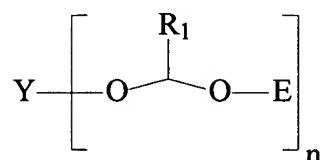
13. (Original) The composition of claim 11, wherein the latent fluxing agent is an α -alkoxyalkyl phenyl ether.

14. (Original) The composition of claim 11, wherein the latent fluxing agent comprises a reaction product of a carboxylic acid and a vinyl ether.

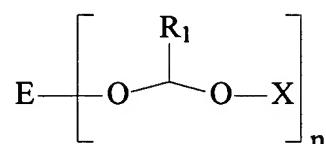
15. (Original) The composition of claim 11,
wherein the latent fluxing agent comprises a composition
selected from a compound having one or more of the following
structures I through VI:



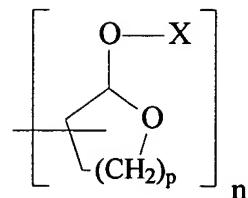
I



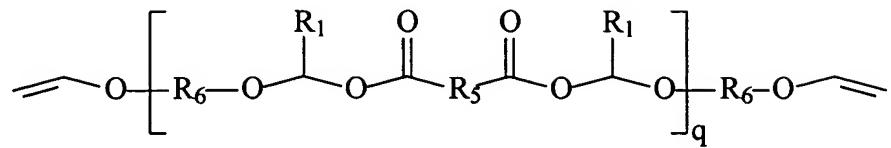
II



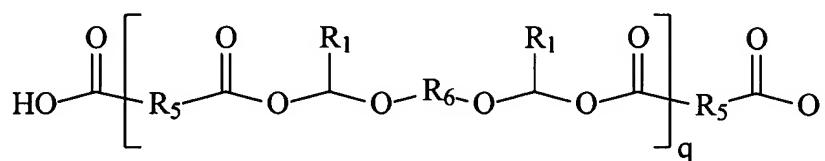
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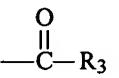
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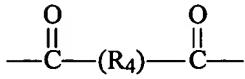
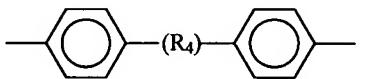


V



VI

wherein X denotes  or ;

Y denotes  or ;

E denotes an organic group derived from a 1-alkenyl ether and may be a hydrocarbon, ether, thioether, ester, thioester, carbamate, amide, or a combination of these groups;

F denotes an organic group fragment derived from a multifunctional 1-cycloalkenyl ether in which the cyclic ether groups are linked though F, and may be a hydrocarbon, ether, thioether, ester, thioester carbamate, amide, or a combination of these groups;

R₁ represents a C₁-C₆ alkyl group;

R² and R³ are independently selected from hydrogen, substituted or unsubstituted linear or branched C₁₋₂₂ alkyl, aryl, alkaryl, cycloalkyl, alkoxy and phenyl;

R₄ is substituted or unsubstituted linear or branched C₁₋₂₂ alkylene, alkenylene, arylene, alkylenearyl, cycloalkylene, alkyleneoxy and phenylene;

R₅ and R₆ are independently selected from linear or branched C₁₋₂₂ alkylene, alkenylene, arylene, alkylenearyl, cycloalkylene, alkyleneoxy and phenylene;

n is an integer from 2-30; p represents the integer 1 or 2 and q is an integer from 5-30.

16. (Original) The composition of claim 15,
wherein the groups E and F include a reactive group selected
from the group consisting of oxirane, thiirane, hydroxyl, amino
and mercapto.

17. (Original) The composition of claim 11,
wherein the epoxy resin in (a) is one or more selected from the
group consisting of bisphenol-A-type epoxy resin, bisphenol-F-
type epoxy resin, phenol novolac-type epoxy resin, cresol
novolac-type epoxy resin, polyepoxy compounds based on aromatic
amines and epichlorohydrin, polyglycidyl derivatives of phenolic
compounds, polyglycidyl derivatives of phenol-formaldehyde
novolacs, polyglycidyl adducts of amines, aminoalcohols and
polycarboxylic acids.

18. (Original) The composition of claim 11
wherein the compound for effecting cure of the epoxy resin in
(c) comprises an epoxy curing agent or catalyst selected from
the group consisting of anhydride compounds, amine compounds,
amide compounds, imidazole compounds, polyfunctional phenols,
carboxylic acids, thiols, and mixtures thereof.

19. (Original) The composition of claim 11,
wherein the compound for effecting cure of the epoxy resin in
(c) is 1,8-diazabicyclo[5.4.0]undec-7-ene.

23. (Original) The composition of claim 11
further comprising an inorganic filler material.

24. (Original) The composition of claim 23,
wherein the inorganic filler material is one or more selected
from the group of materials constructed of or containing
reinforcing silicas, aluminum oxide, silicon nitride, aluminum
nitride, silica-coated aluminum nitride and boron nitride.

25. (Original) A thermoset resin comprising a
reaction product of the composition of claim 11.

26. (Original) A one component curable
composition comprising:

(a) from about 15 percent to about 75 percent,
based on the total weight of the composition, of an epoxy
resin;

(b) from about 10 percent to about 70 percent,
based on the total weight of the composition, of a thermally
labile compound selected from the group consisting of (a) an
 α -alkoxyalkyl ester reaction product of a carboxylic acid and
a vinyl ether, and (b) an α -alkoxyalkyl phenyl ether reaction
product of a phenolic acid and a vinyl ether;

(c) a compound for effecting cure of the epoxy
resin selected from an epoxy curing agent in an amount of from
about 0.15 to about 1.5 equivalents per equivalent of epoxide,
or an epoxy curing catalyst in an amount of from about 0.02

percent to about 20 percent by weight of the epoxy component, or combinations thereof;

(d) from about 1 percent to about 70 percent, based on the total weight of the composition, of an inorganic filler material; and

(e) optionally, from about 1 percent to about 20 percent, based on the total weight of the composition, of an epoxy resin adduct of a carboxyl terminated toughening agent.

27. (Original) The composition of claim 26, wherein the thermally labile compound (b) includes one or more functional groups capable of reacting into a cured epoxy composition.

28. (Original) The composition of claim 27, wherein the thermally labile compound (b) includes an epoxy functional group.